SPECIFICATION

DEVICE NAME : Power MOSFET

TYPE NAME : 2SK2524-01MR

SPEC. No. :

Fuji Electric Co.,Ltd.

This Specification is subject to change without notice.

	DATE	NAME	APPROVED
DRAWN			
CHECKED			

Fuji Electric Co.,Ltd.

DWG.NO.

1. Scope
   This specifies Fuji power MOSFET 2SK2524-01MR

2. Construction N-channel enhancement mode power MOSFET

3. Application for switching

4. Outview TO-220F Outviwe See to 5/11 page

5. Absolute maximum ratings at Tc=25℃ (unless otherwise specified)

Description	Symbol	Characteristics	Unit	Remarks
Drain-source voltage	V_{DS}	450	V	
Drain-gate voltage	V_{DGR}	450	V	R_{GS}=20KΩ
Continuous Drain current	I_D	± 9	A	
Pulsed drain current	I_{Dpulse}	± 36	A	
Gate-source voltage	V_{GS}	± 30	V	
Maximum power dissipation	P_D	40	W	
Operating and storage temperature range	T_{ch}	150	℃	
	T_{stg}	-55 ~ +150	℃	

6. Electrical characteristics at Tc=25℃ (unless otherwise specified)
   Static ratings

Description	Symbol	Conditions		Characteristics			Unit
				Min.	Typ.	Max.	
Drain-source breakdown voltage	BV_{DSS}	I_D =1mA V_{GS}=0V		450			V
Gate threshold voltage	$V_{GS}(th)$	I_D =1mA V_{DS}=V_{GS}		2.5	3.0	3.5	V
Zero gate voltage drain current	I_{DSS}	V_{DS}=450V V_{GS}= 0V	T_{ch}= 25℃			500	μA
	I_{DSS}		T_{ch}=125℃			1.0	mA
Gate-source leakage current	I_{GSS}	V_{GS}=±30V V_{DS}= 0V			10	100	nA
Drain-source on-state resistance	$R_{DS}(on)$	I_D =4.5A V_{GS}=10 V			0.87	1.0	Ω

Dynamic ratings

Description	Symbol	Conditions	Characteristics			Unit
			Min.	Typ.	Max.	
Forward transconductance	gfs	I_D =4.5A V_{DS}=25 V	3.0	6.6		S
Input capacitance	Ciss	V_{DS}=25V V_{GS}= 0V f =1MHz		1150	1700	pF
Output capacitance	Coss			130	200	pF
Reverse transfer capacitance	Crss			50	75	pF
Turn-on time	td(on)	V_{CC}=300V V_{GS}= 10V I_D = 9A R_{GS}= 10Ω		20	30	ns
	tr			50	75	ns
Turn-off time	td(off)			60	90	ns
	tf			35	55	ns

Reverse diode

Description	Symbol	Conditions	Characteristics			Unit
			Min.	Typ.	Max.	
Avalanche capability	I_{AV}	L= 100μH, T_{ch}= 25℃ ‡ see Fig1 and Fig2	9.0			A
Diode forward on-voltage	V_{SD}	I_F = 2 × I_{DR} V_{GS}=0V, T_{ch}=25℃		1.1	1.65	V
Reverse recovery time	t_{rr}	I_F = I_{DR} V_{GS}=0V $-dI_F/dt$=100A/μs T_{ch}=25℃		550		ns
Reverse recovery charge	Q_{rr}			3.9		μC

7. Thermal resistance

Description	Symbol	Conditions	Characteristics			Unit
			Min.	Typ.	Max.	
Thermal resistance	$R_{th\,ch-c}$				3.125	℃/W
	$R_{th\,ch-a}$				62.5	℃/W

Fig. 1 Test circuit

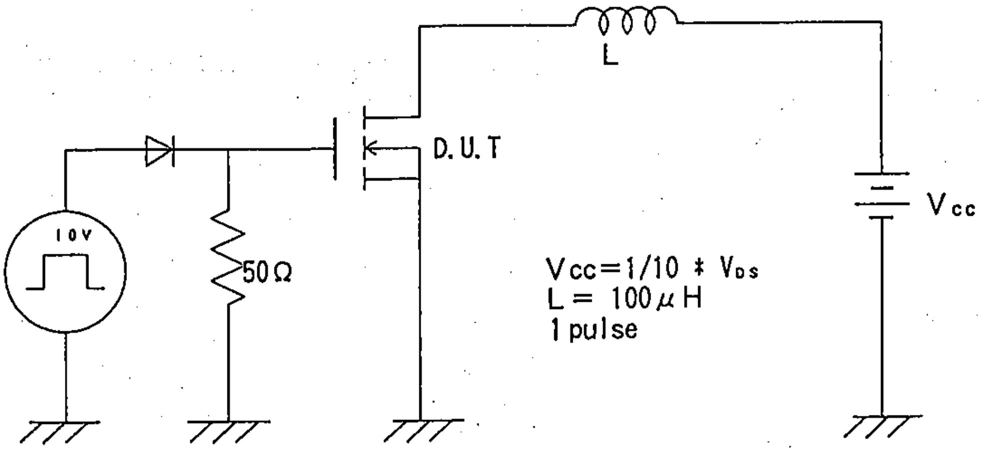
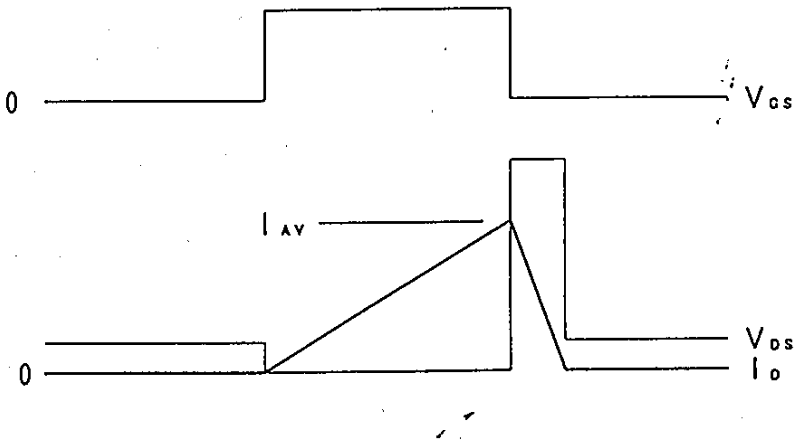
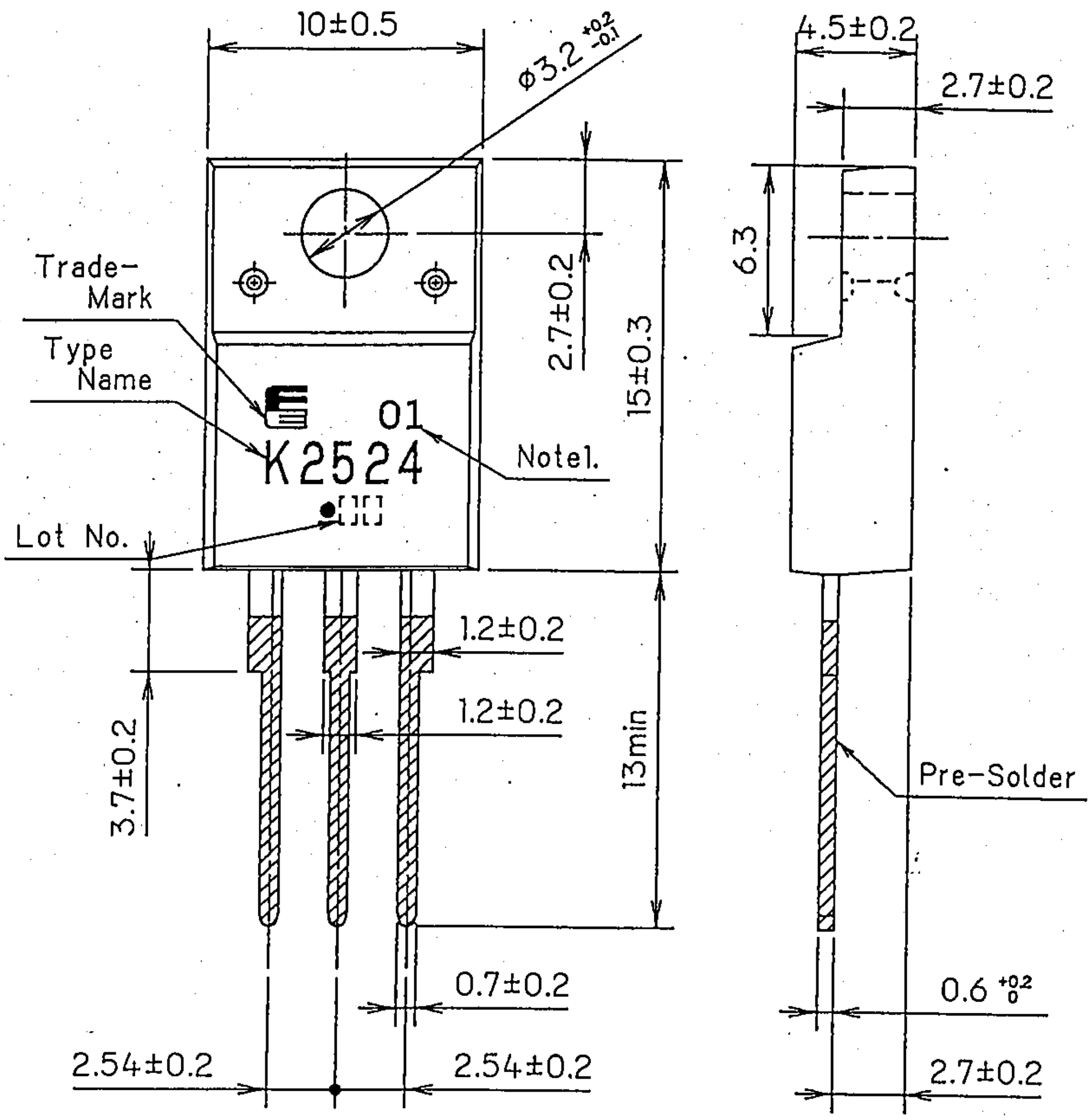


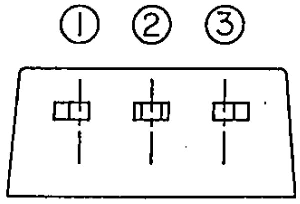
Fig. 2 Operating waveforms



FUJI POWER MOS FET

TYPE : 2SK2524-01MR





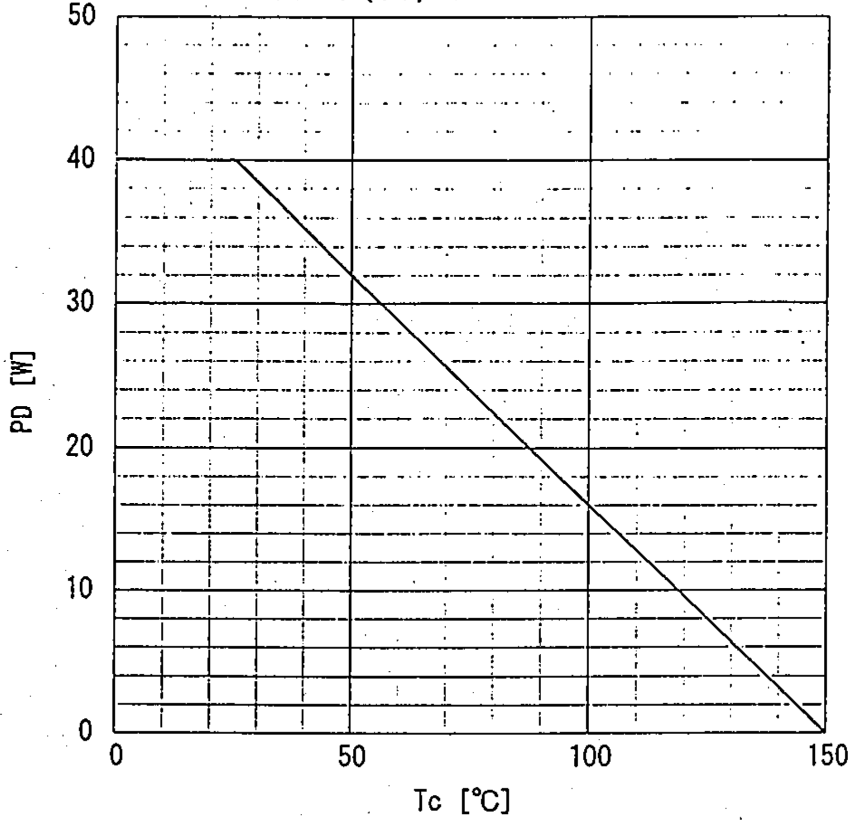
CONNECTION

① GATE
② DRAIN
③ SOURCE

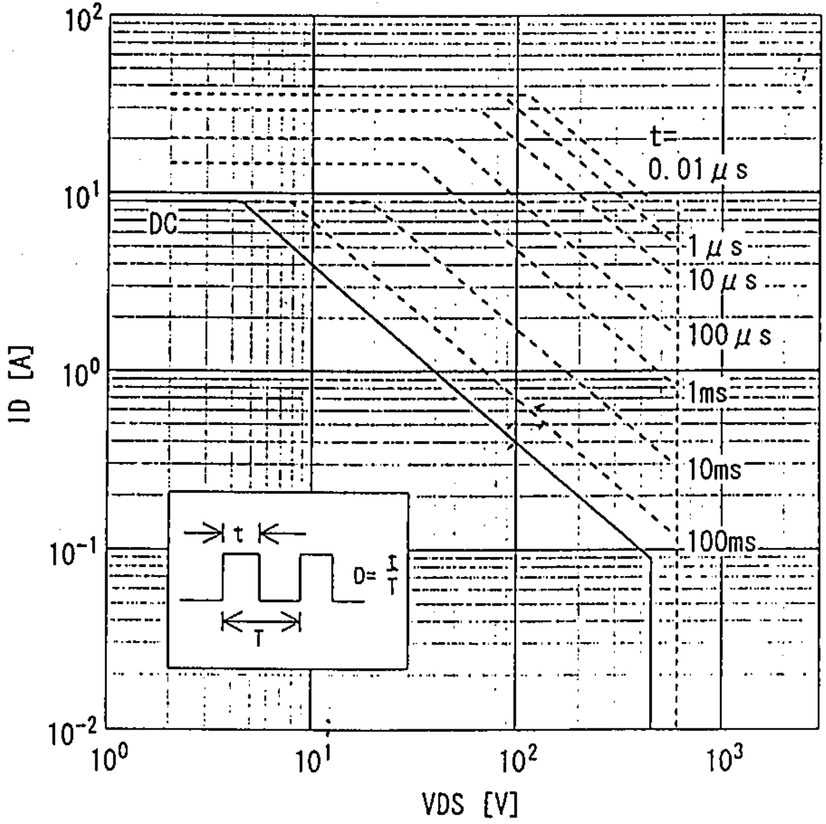
Note 1. Guaranteed mark of avalanche ruggedness.

DIMENSIONS ARE IN MILLIMETERS.

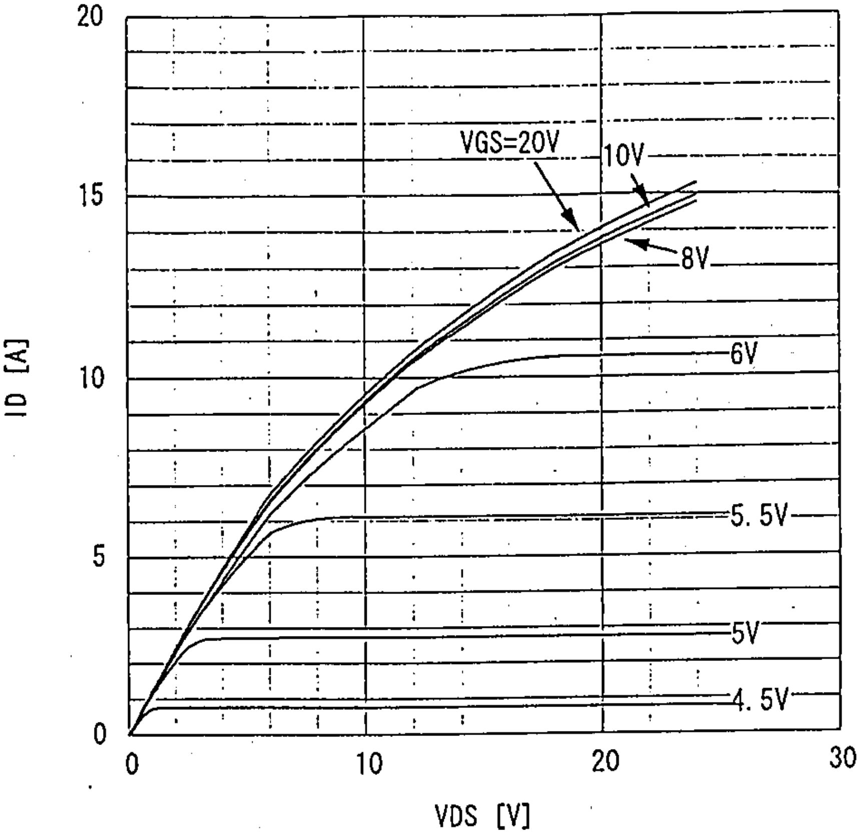
Power Dissipation
PD=f(Tc)



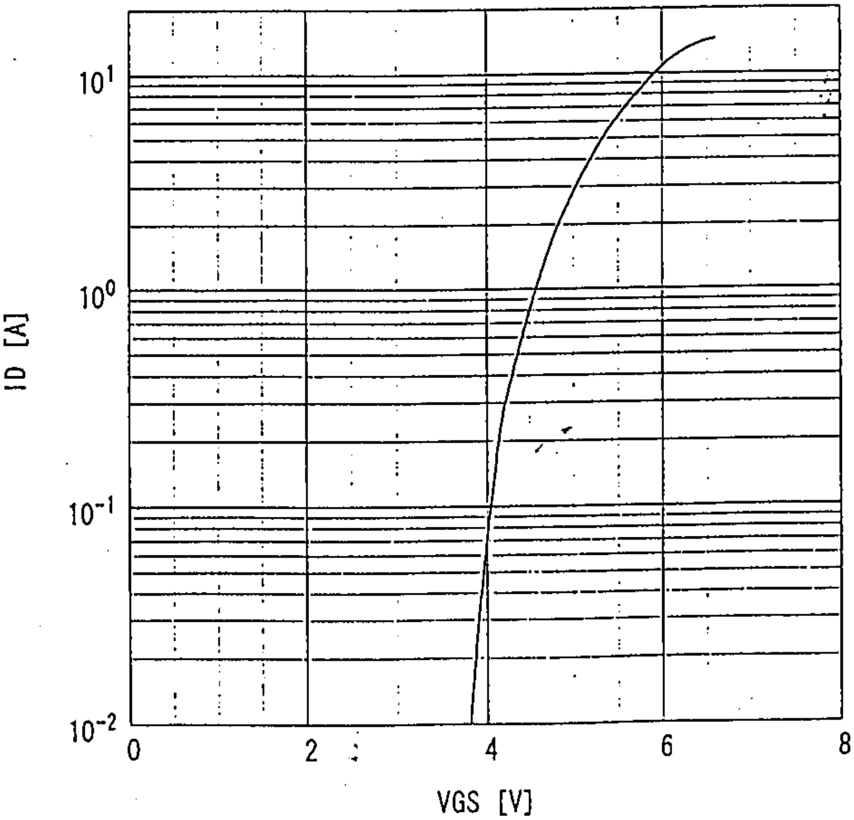
Safe operating area
ID=f(VDS):D=0.01,Tc=25℃



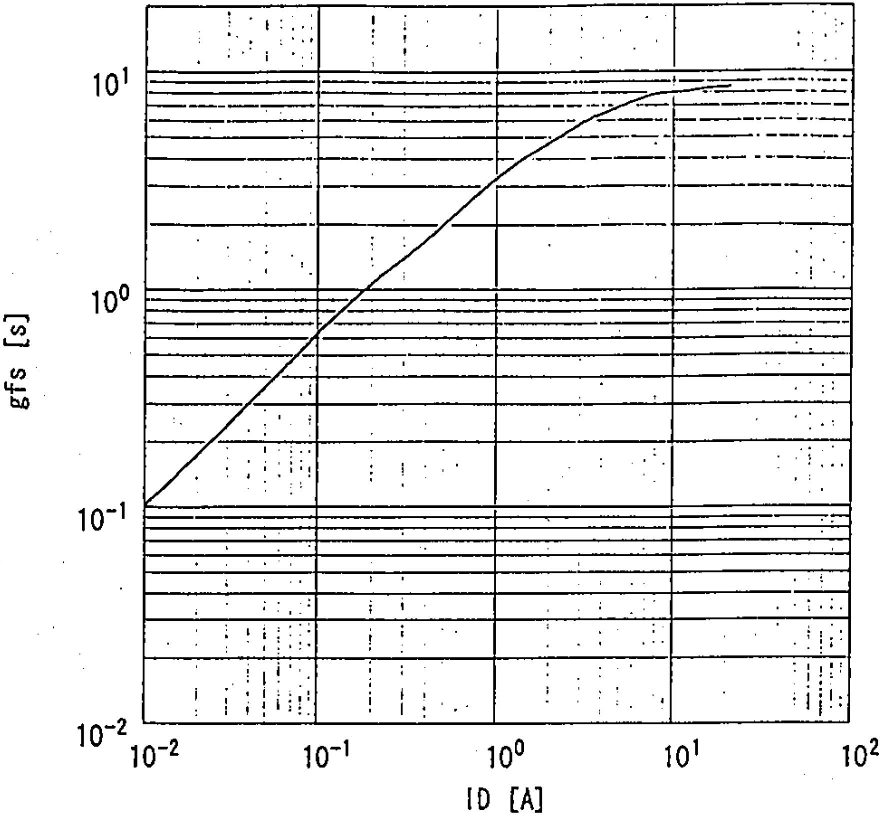
Typical output characteristics
ID=f(VDS):80μs pulse test, Tc=25℃



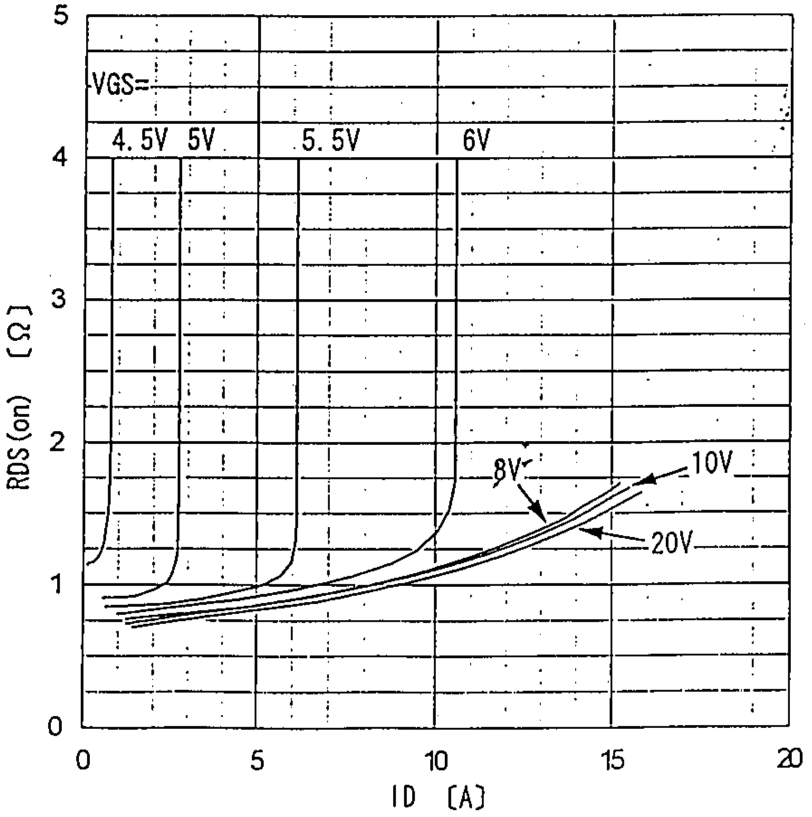
Typical transfer characteristic
ID=f(VGS):80μs pulse test, VDS=25V, Tch=25℃



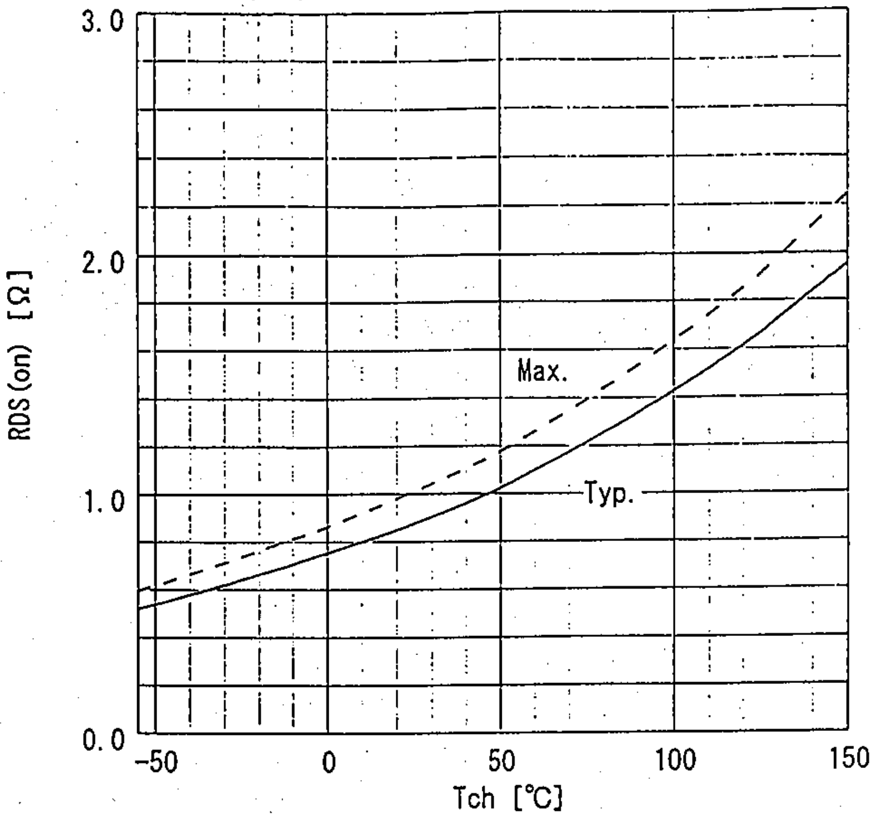
Typical forward transconductance
gfs=f(ID):80μs pulse test, VDS=25V, Tch=25℃



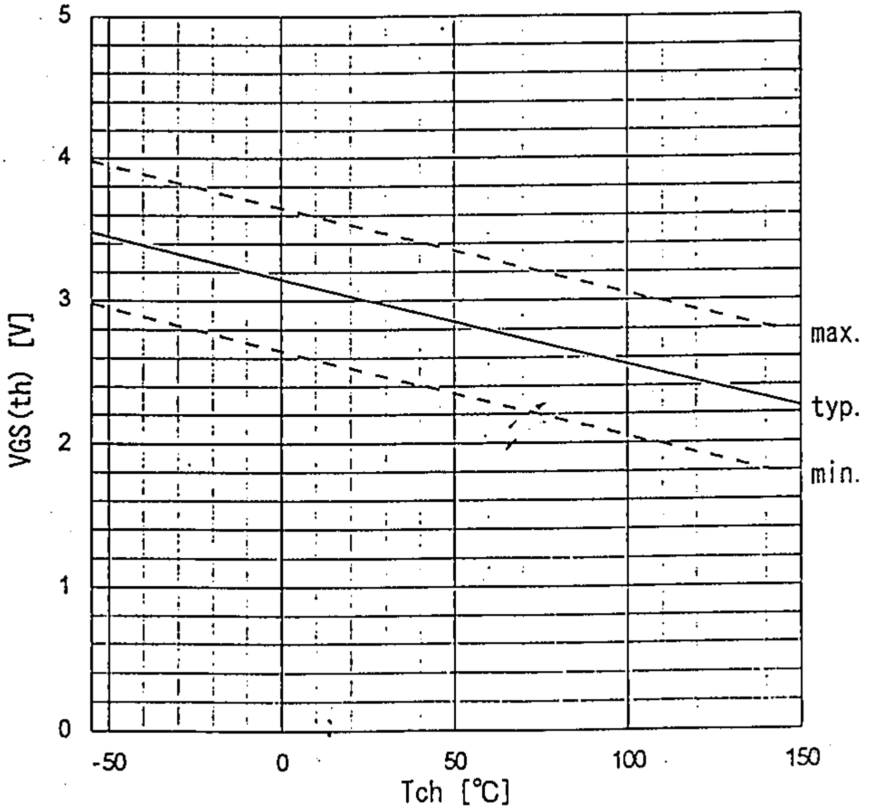
Typcal drain-source on-state resistance
RDS(on)=f(ID):Tch=25℃



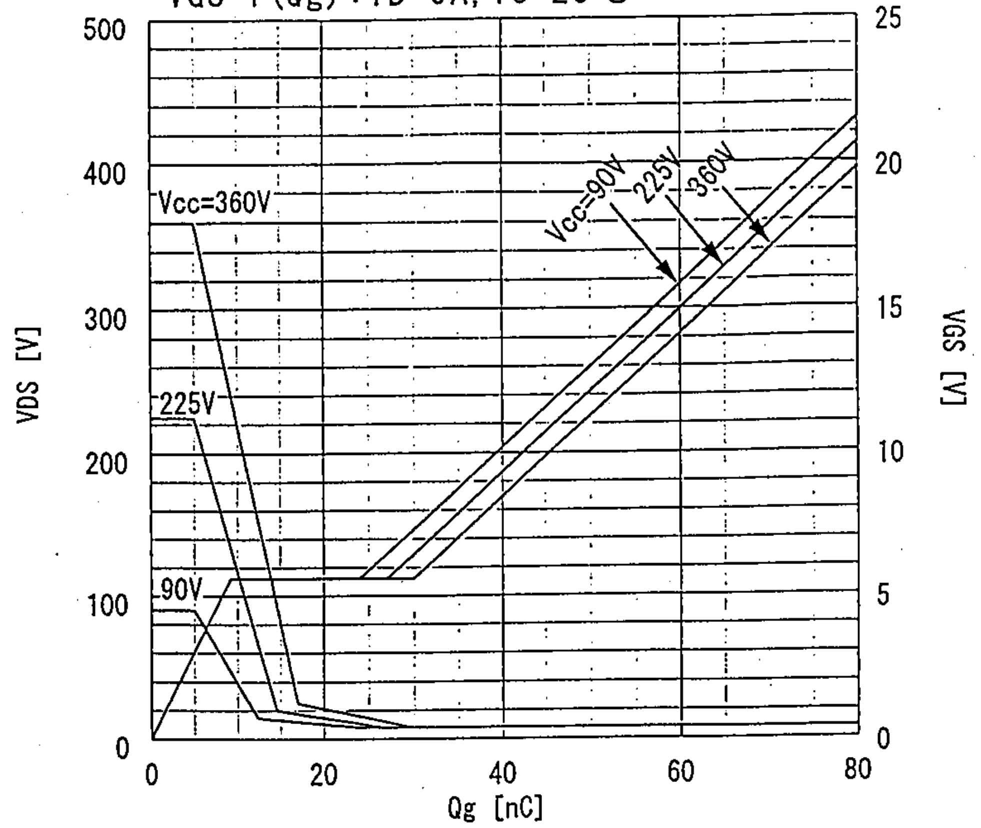
Drain-source on-state resistance
RDS(on)=f(Tch):ID=4.5A, VGS=10V



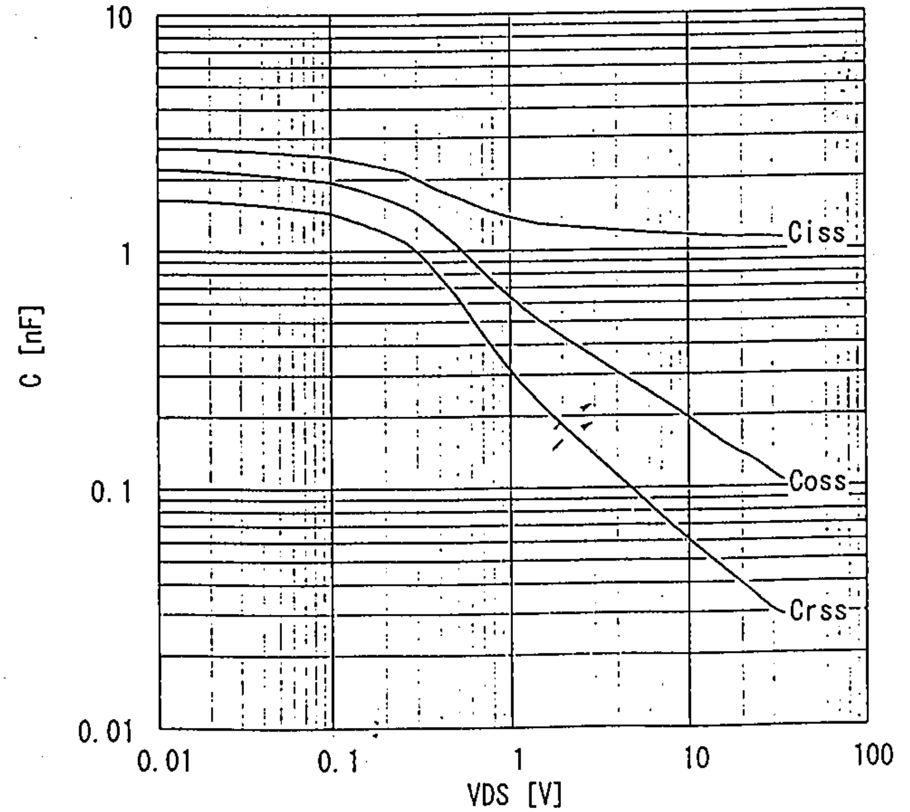
Gate threshold voltage
VGS(th)=f(Tch):ID=1mA, VDS=VGS



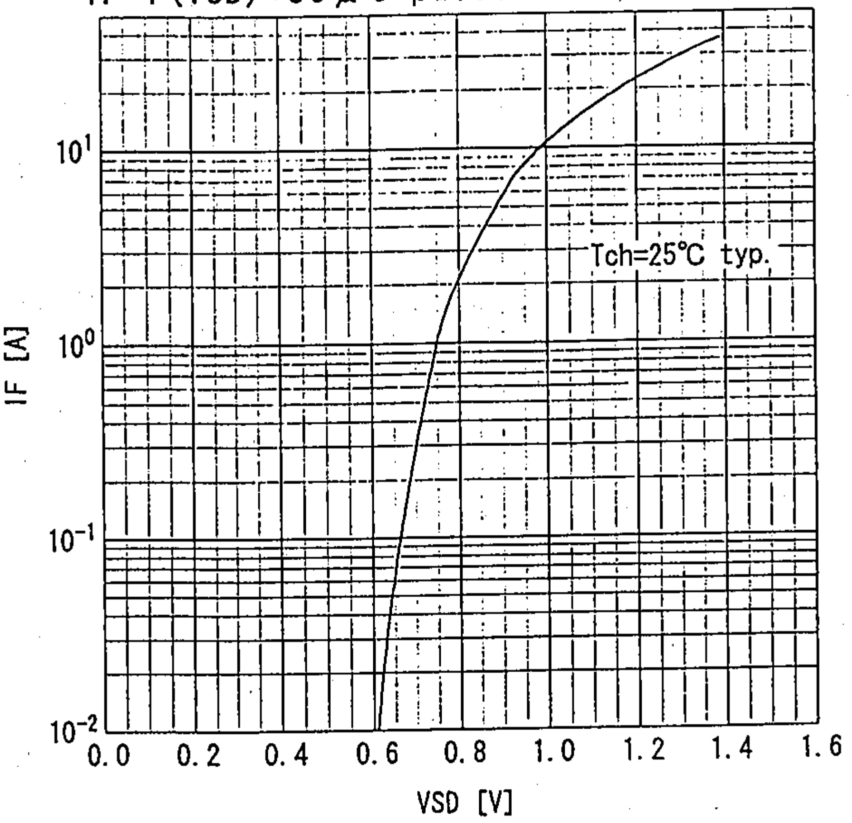
Typical gate charge characteristic
VGS=f(Qg):ID=9A, Tc=25℃



Typical capacitances
C=f(VDS):VGS=0V, f=1MHz



Forward characteristic of reverse diode
IF=f(VSD):80μs pules test, VGS=0V



Transient thermal impedance
Zthch=f(t) parameter:D=t/T